

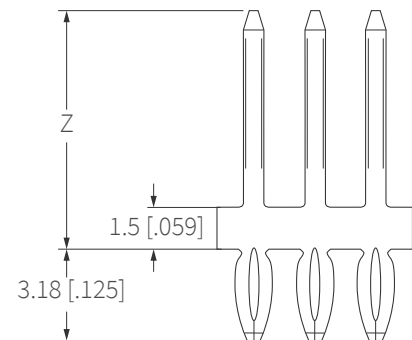
DUAL COMPLIANT PRESS-FIT TERMINAL SPECIFICATIONS

TYPE	PART NUMBER	MATERIAL	SIZE	Z LENGTH		PCB HOLE SIZE	CARRIER TYPE	CURRENT CAPACITY STANDARD	CURRENT CAPACITY HI-TEMP
				MM	INCH				
Dual Compliant	7-V5045-004NN	Standard	.64 Dual	1.85	0.073	A	Side Carrier	10 A	20 A
	7-V5019-004TT	Standard	.81 Dual	1.57	0.062	B	Side Carrier	22 A	44 A
	7-V5019-094AA	Standard	.81 Dual	10.50	0.413	B	Side Carrier	14 A	28 A

NOTE:

1. Current Carrying Capacity (Current Rating) for $\Delta T = 30^{\circ}\text{C}$ Heat Rise
2. Current Carrying Capacity (Current Rating) for C42520 is defined per: SAE/USCAR-2 - Revision 5 - Section 5.3.3, EIA Publication 364 - Procedure 70 thru the testing
3. Current Carrying Capacities (Current Rating) for C19010 are defined using C42520 data and theoretical formula
4. All current ratings must be verified during validation testing of the final assembly

Side Carrier



PRESS-FIT PCB HOLE SIZE REQUIREMENTS

HOLE SIZE	COMPONENT THICKNESS	FINISHED HOLE DIAMETER	DESCRIPTION	PC BOARD DIMENSIONS
A	0.64 mm	1.05 mm	Drilled Hole	1.15 ± 0.025 mm
			Copper Plating	
			Plating Thickness	25 µm min
			Hole Diameter	1.05 ± 0.05 mm
			Finished Hole	
			Tin Plating Thickness	2 µm-8 µm
			Plated Hole Diameter	1.05 ± 0.05 mm
			Precious metal Plated (Note 2)	1.05 ± 0.05 mm
B	0.81 mm	1.50 mm	Drilled Hole	1.60 ± 0.025 mm
			Copper Plating	
			Plating Thickness	25 µm min
			Hole Diameter	1.50 ± 0.05 mm
			Finished Hole	
			Tin Plating Thickness	2 µm-8 µm
			Plated Hole Diameter	1.50 ± 0.05 mm
			Precious metal Plated (Note 2)	1.50 ± 0.05 mm

NOTE:

1. Tin thickness applies to tin-lead and lead free plating.
2. Precious metal plating types:

Immersion Au:

0.08 µm-0.13 µm [3 µin-5 µin] Gold over
3.8 µm-7.6 µm [150 µin-300 µin] Nickel

Immersion Ag:

0.2 µm-0.5 µm [8 µin -20 µin]